

FIBCOOL Thin-Film Type



Ultra-low Thermal Resistance

Ultra-thin 0.1mm or below
Excellent insulation

Item	Unit	Characteristic Value
Thickness	mm	0.08, 0.1, 0.15, 0.2
Thermal Conductivity	W/m · K	4.6
Thermal Resistance	°C · cm ² / W	1.60 (at 350kPa)
Density	g / cm ³	2.26
Hardness	°	74 (Shore DD)
Tensile Strength	MPa	0.76
Dielectric Strength	kV/mm	24.0 (at 0.1mm)
Dielectric Constant	-	3.1 (1MHz)
Dielectric Loss Tangent	-	9.6 × 10 ⁻³ (1MHz)

※These are measured values, not product specification values.

Features

Ultra-thin ·
0.1mm or below
Ultra-low
thermal resistance

Strong
High elastic recovery
resists tearing

Flexible
High density
contact

Benefits

- 01 Dramatically improved cooling efficiency
- 02 Conforms perfectly even under low compression
- 03 Can be applied to curved surfaces
- 04 Reliable even under high compression
- 05 Excellent durability and ease of use
- 06 Secondary processing & drilling possible

Applications



Optical
Transceivers



SSD



Medical devices



LD



LED

